

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chong Zhang</td> <td>04/11/2013</td> </tr> <tr> <td>Stefanie M. Lotz</td> <td>04/11/2013</td> </tr> <tr> <td>Islam A. Salama</td> <td>04/11/2013</td> </tr> </tbody> </table>		Name	Execution Date	Chong Zhang	04/11/2013	Stefanie M. Lotz	04/11/2013	Islam A. Salama	04/11/2013		
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RECEIVING PARTY DATA											
<table border="1"> <tr> <td>Name:</td> <td>Intel Corporation</td> </tr> <tr> <td>Street Address:</td> <td>2200 Mission College Boulevard</td> </tr> <tr> <td>City:</td> <td>Santa Clara</td> </tr> <tr> <td>State/Country:</td> <td>CALIFORNIA</td> </tr> <tr> <td>Postal Code:</td> <td>95054</td> </tr> </table>		Name:	Intel Corporation	Street Address:	2200 Mission College Boulevard	City:	Santa Clara	State/Country:	CALIFORNIA	Postal Code:	95054
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PROPERTY NUMBERS Total: 1											
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CORRESPONDENCE DATA											
<p>Fax Number: 5037962900 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 503-222-9981 Email: adahmen@schwabe.com Correspondent Name: Schwabe, Williamson & Wyatt, P.C. Address Line 1: 1211 SW 5th Avenue, Suite 1900 Address Line 4: Portland, OREGON 97204</p>											
ATTORNEY DOCKET NUMBER:	111079-189922										
NAME OF SUBMITTER:	Allyson Dahmen										
Signature:	/Allyson Dahmen/										
Date:	05/23/2013										
Total Attachments: 2 source=P54648 Assignment#page1.tif source=P54648 Assignment#page2.tif											

CH \$40.00 13870874

A S S I G N M E N T

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged that the undersigned,

ASSIGNOR(S): Chong Zhang
Stefanie M. Lotz
Islam A. Salama

hereby sell, assign, and transfer to

ASSIGNEE: Intel Corporation
2200 Mission College Boulevard
Santa Clara, California 95054

and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements that are disclosed in the application for the United States patent entitled:

***PACKAGE SUBSTRATE WITH HIGH DENSITY INTERCONNECT DESIGN TO
CAPTURE CONDUCTIVE FEATURES ON EMBEDDED DIE***

(I hereby authorize and request my attorney, associated with Customer Number 0031817, to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on April 25, 2013 as
United States Application Number 13/870,874 and

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

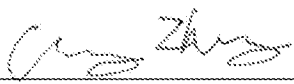
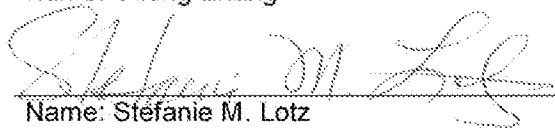
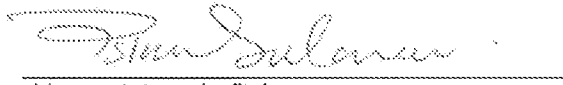
and in and to said application and all divisional applications, continuation applications, continued prosecution applications, continuation-in-part applications, substitute applications, renewal applications, reissue applications, reexaminations, extensions, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original patents, reissued patents, reexamination certificates, and extensions, that have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application;

agree that said Assignee may apply for and receive a patent or patents for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional

applications, continuation applications, continued prosecution applications, continuation-in-part applications, substitute applications, renewal applications, reissue applications, reexaminations, extensions and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and representatives all facts known to the undersigned relating to said improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or representatives in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Inventor: Please sign and date below:

<u>4/11/2013</u> Date	<u></u> Name: Chong Zhang
<u>4/11/2013</u> Date	<u></u> Name: Stefanie M. Lotz
<u>4/11/2013</u> Date	<u></u> Name: Islam A. Salama

Assignment Document Return Address:

Schwabe, Williamson & Wyatt, P.C.
Pacwest Center, Suite 1600
1211 SW Fifth Avenue
Portland, Oregon 97204
Telephone: 503-222-9981